



**FOR IMMEDIATE RELEASE**

**EV GROUP UNVEILS NEXT-GENERATION TEMPORARY BONDING AND DEBONDING PLATFORM FOR HIGH-VOLUME 3D IC MANUFACTURING**

***Enhanced Hardware, Software and Process Control Capabilities Enable Two-fold Increase in Throughput to Meet Productivity and Yield Requirements of Today's 3D IC Manufacturers***

**ST. FLORIAN, Austria, July 3, 2012** — EV Group (EVG), a leading supplier of wafer bonding and lithography equipment for the MEMS, nanotechnology and semiconductor markets, today introduced the EVG<sup>®</sup> 850TB/DB automated temporary bonding and debonding system built on the company's new [XT Frame platform](#), which has been optimized to support thin-wafer processing for high-volume 3D IC and TSV (through silicon via) manufacturing. A combination of hardware and software design enhancements enables double the processing throughput over EVG's previous-generation, industry-benchmark platform to up to 40 stacks per hour. The new [XT Frame-configured EVG850TB/DB](#) is designed for EV Group's open materials platform approach, which enables the use of a wide range of adhesives from various materials suppliers. This approach provides customers with the most flexible choice of bonding materials supporting [ZoneBOND™](#) and other technologies—and is key to achieving high process throughput, repeatability and yields for 3D IC manufacturing.

"Temporary bonding and debonding of device wafers to wafer carriers for thin-wafer processing are critical steps to enabling the successful integration and implementation of 3D ICs into high-volume production," stated Dr. Thorsten Matthias, Business Development Director, EV Group. "To this end, advances in wafer bonding are necessary to support the efforts of early 3D IC/TSV adopters as they move ever-closer to attaining this goal. Our new XT Frame-configured EVG850TB/DB builds upon our core expertise to provide production-ready solutions for our customers to facilitate their rapid ramp from development and integration to high-volume manufacturing. It is designed from the ground up to enable the highest productivity and yields in thin-wafer processing."

Built on the company's new XT Frame platform, the EVG850TB/DB is capable of accommodating up to nine process modules, doubling the previous maximum processing capability of EVG's temporary bonding and debonding systems. The new XT Frame design enables highly efficient continuous mode operation (zero idle time) capability via an ultra-fast handling system, up to four FOUP (front opening unified pod) load ports, and a material buffer in the form of a local FOUP storage system that holds up to 10 additional FOUFs. The platform also features an in-line metrology module option to enable real-time monitoring of the bonding/debonding process—enabling maximum yields and helping to lower production costs for thin-wafer processing. In addition, the EVG850TB/DB has been qualified for all bonding and debonding methods, including low temperature debonding methods like ZoneBOND™ technology with EZR<sup>®</sup> (Edge Zone Release) and EZD<sup>®</sup> (Edge Zone Debond) modules.

The EVG850TB/DB built on the new XT Frame platform is now available for shipping. EV Group has provided leading-edge temporary bonding and debonding solutions for 15 years—and is the first to provide its high-volume manufacturing customers with a TB/DB solution for around-the-clock operation.

**About EV Group (EVG)**

EV Group (EVG) is a world leader in wafer-processing solutions for semiconductor, MEMS and nanotechnology applications. Through close collaboration with its global customers, the company implements its flexible manufacturing model to develop reliable, high-quality, low-cost-of-ownership systems that are easily integrated into customers' fab lines. Key products include wafer bonding, lithography/nanoimprint lithography (NIL) and metrology equipment, as well as photoresist coaters, cleaners and inspection systems.

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In addition to its dominant share of the market for wafer bonders, EVG holds a leading position in NIL and lithography for advanced packaging and MEMS. Along these lines, the company co-founded the EMC-3D consortium in 2006 to create and help drive implementation of a cost-effective through-silicon via (TSV) process for major ICs and MEMS/sensors. Other target semiconductor-related markets include silicon-on-insulator (SOI), compound semiconductor and silicon-based power-device solutions.

Founded in 1980, EVG is headquartered in St. Florian, Austria, and operates via a global customer support network, with subsidiaries in Tempe, Ariz.; Albany, N.Y.; Yokohama and Fukuoka, Japan; Seoul, Korea and Chung-Li, Taiwan. More information is available at [www.EVGroup.com](http://www.EVGroup.com).

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